



Integrated Thin-Film Resistor Materials for High-Frequency Applications

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- Why AESA Radar Performance is Getting Harder

- Hidden Cost of Discrete RF Resistors

Embedded Resistors: From Lumped Components to Planar RF Elements

- Electrical Comparison

- Reliability Comparison

Resistor Tolerance

- Design Checklist

- Wilkinson Power Divider Test Plan

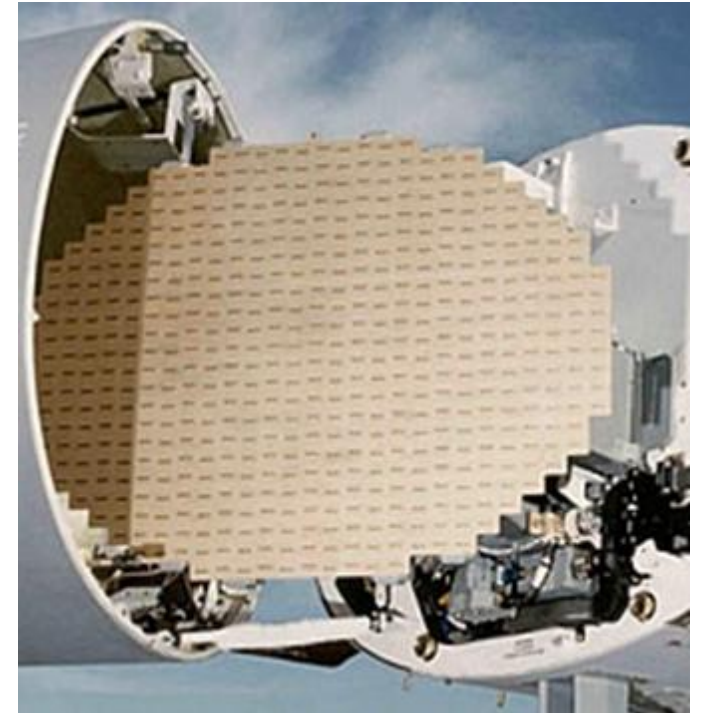
- Material Options

- Summary

- Q&A



- Higher frequencies (X → Ka → mmWave)
- Larger arrays, tighter phase budgets
- Increased channel density
- Calibration stability challenges

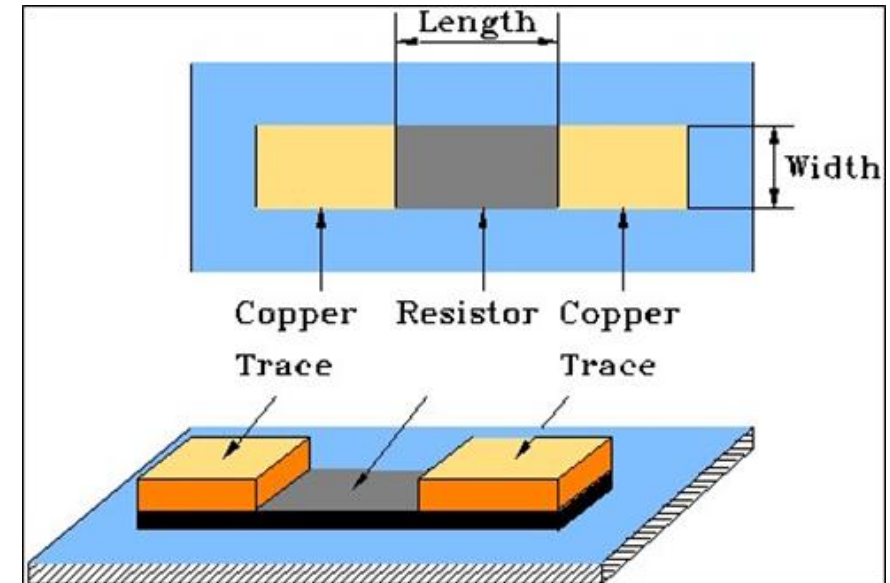


- Parasitic inductance and capacitance
- Via transitions in RF paths
- Solder joint variability
- Assembly-driven mismatch



Embedded Resistors: From Lumped Components to Planar RF Elements

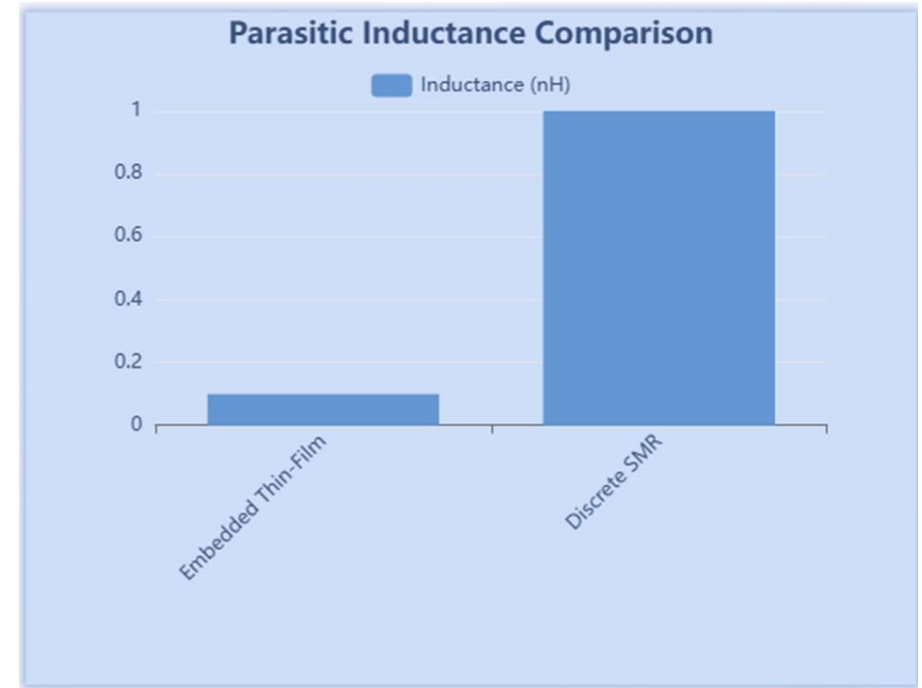
- Planar, lithographically defined
- No solder joints
- No vias in signal path
- Geometry-controlled resistance



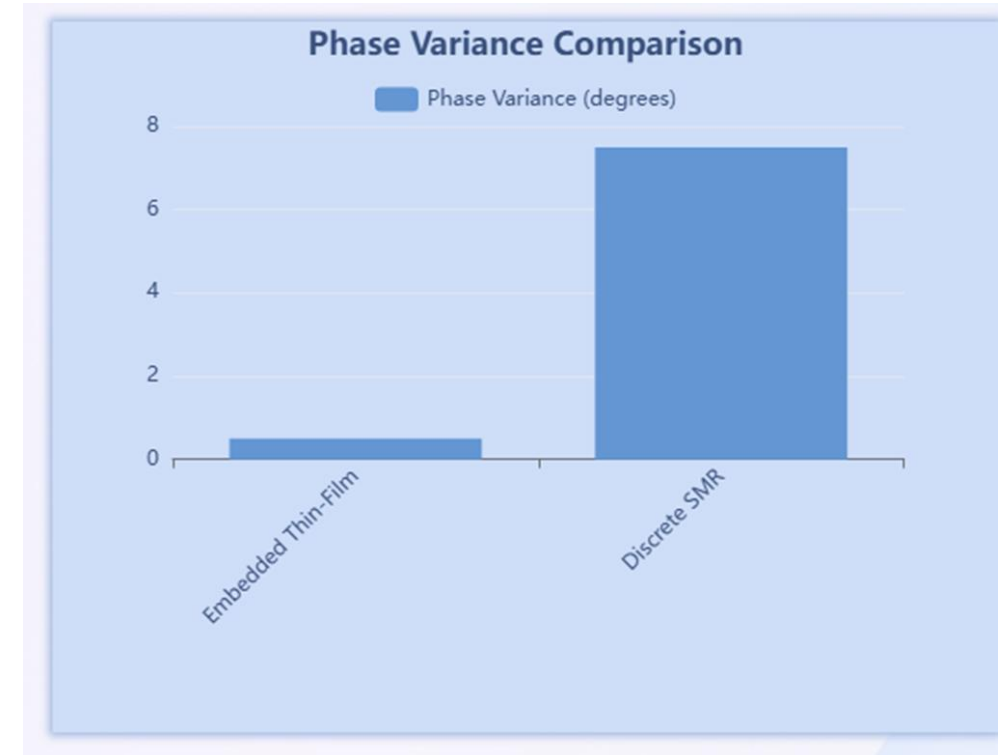
- Embedded thin-film resistors outperform discrete SMRs in critical RF metrics
- Near-zero parasitic inductance (**< 0.1 nH vs 0.5–1.0 nH**)
- Lower insertion loss (**< 0.05 dB @ 40 GHz vs 0.1–0.2 dB**)
- Improved phase consistency (**$\pm 0.5^\circ$ vs $\pm 5\text{--}10^\circ$**)
- No surface board area required (embedded structure)
- Eliminates solder fatigue risk
- Excellent thermal stability



- Embedded resistors reduce parasitic inductance by up to **90%**
- Typical values:
- Embedded: **< 0.1 nH**
- Discrete SMR: **~1.0 nH**
- Critical for signal integrity above 40 GHz
- Enables improved high-frequency consistency
- Reduces impedance distortion in RF signal paths

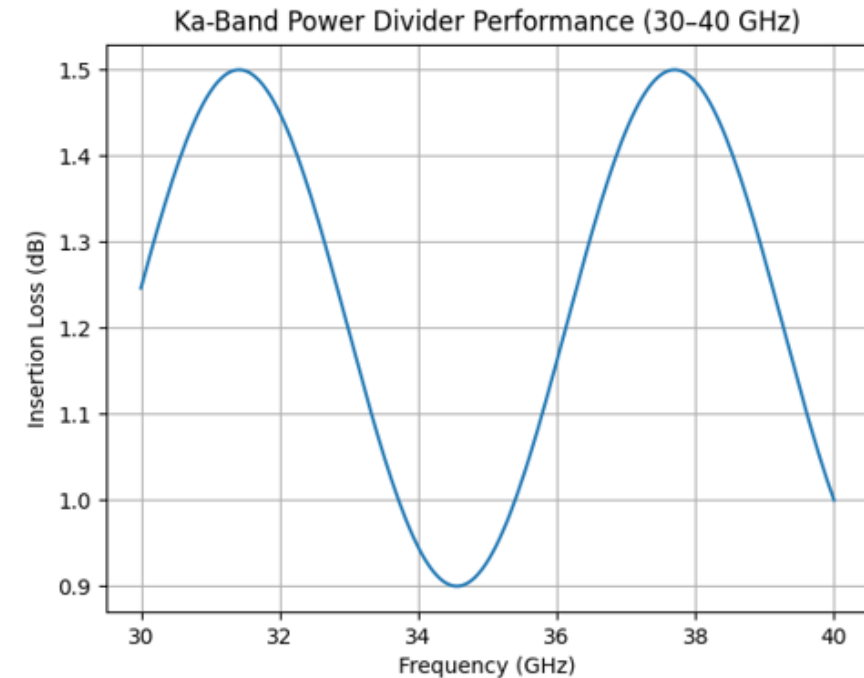


- Up to 15× improvement in phase consistency vs discrete SMRs
- Embedded: $\pm 0.5^\circ$ typical variance
- Discrete SMR: $\pm 7.5^\circ$ average variance
- Reduces need for post-fabrication calibration
- Improves uniformity across array channels
- Enhances beamforming accuracy



Ka-Band Power Divider Performance (30-38 GHz)

- 3-way power divider demonstration
- **23.5%** operational bandwidth
- **< 2 dB** transmission loss
- **± 0.55 dB** amplitude balance
- Demonstrates low-loss embedded resistor performance
- Validates suitability for Ka-band radar applications



- 4× reduction in insertion loss vs discrete SMRs
- Embedded: < **0.05 dB @ 40 GHz**
- Discrete: ~**0.2 dB @ 40 GHz**
- Improves system-level RF efficiency
- Extends operational range
- Reduces RF power consumption



Phased-array transceivers (26–40 GHz)

- Uniform gain and phase
- Reduced mismatch

Wilkinson power dividers (2–40 GHz)

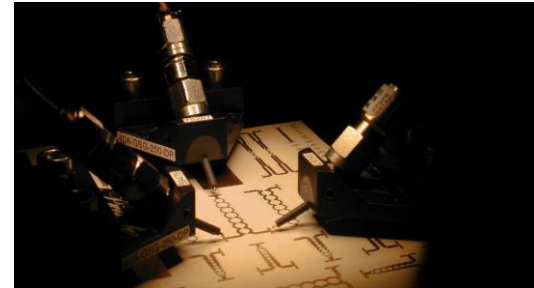
- High isolation
- Minimal footprint

Beamforming networks (~28 GHz)

- Compact, low-loss integration

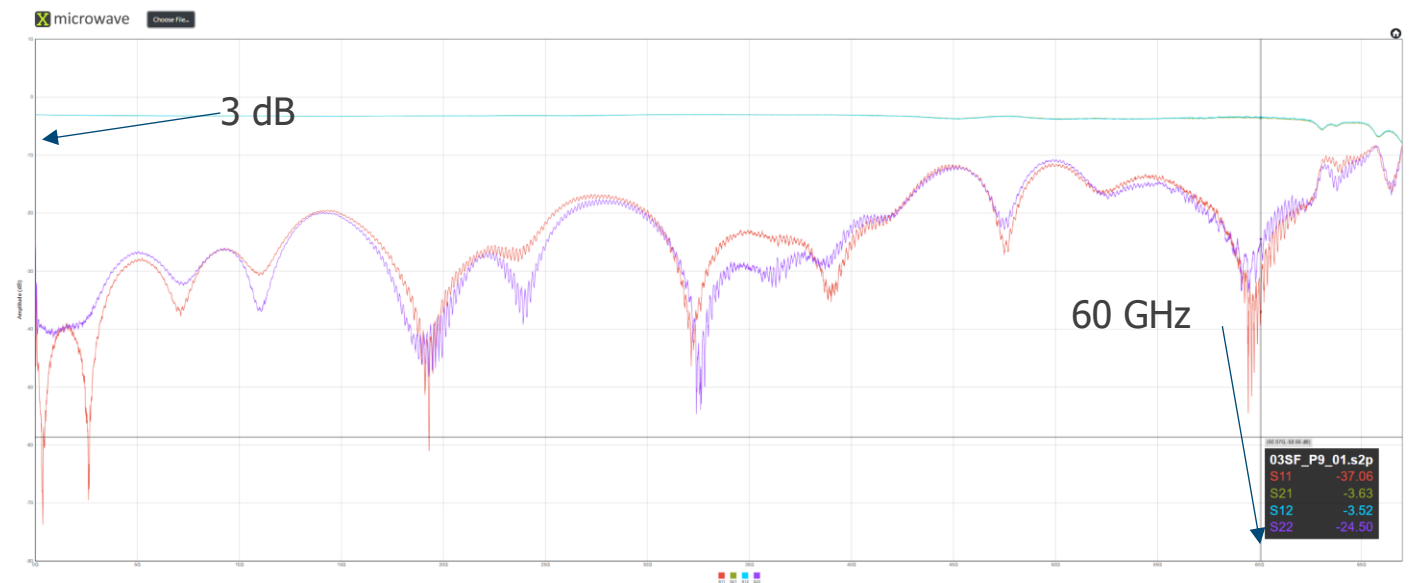
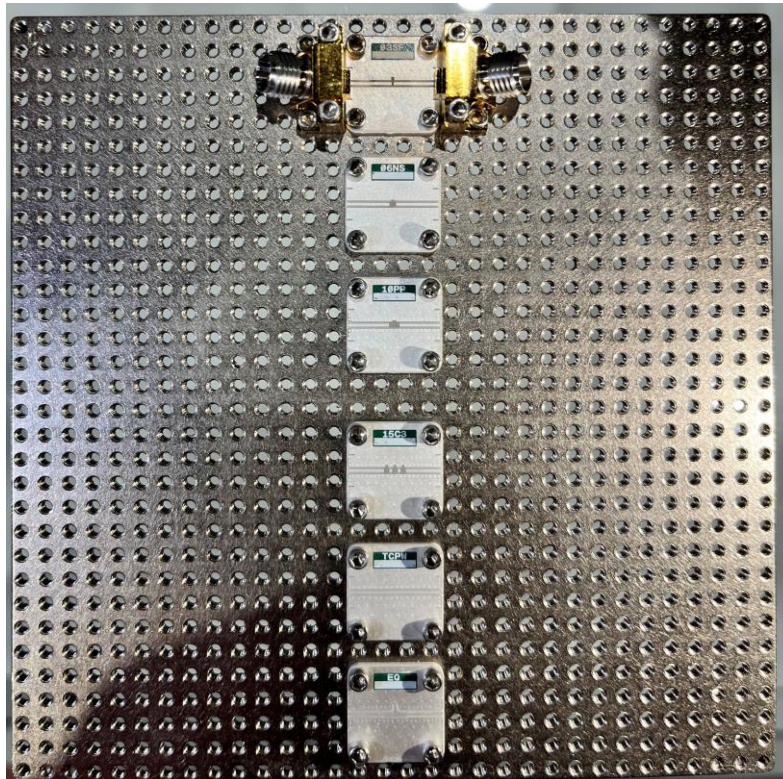
Aerospace & defense modules (X / Ka-band)

- Lightweight, high-reliability builds

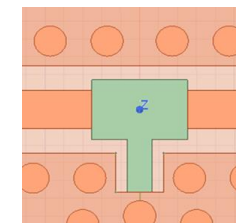
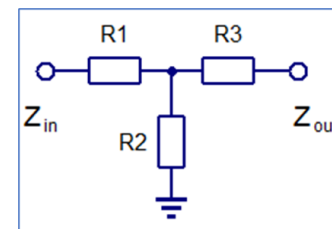


Measured RF Performance (Example: Attenuator)

- Attenuator utilized a 3-resistor design (2 in series and 1 to ground)
- Designed for 3 dB up to 60 GHz
- Simulated and actual performance in agreement with excellent results



03SF_P9_01.s2p X	S11	S21	S12	S22
S11	-37.06			
S21		-3.63		
S12			-3.52	
S22				-24.50



- No solder fatigue
- No vibration-induced failures
- Stable over temperature cycling
 - Resistance Temperature Coefficient <110 ppm/°C (-55 to 125 °C)
 - Tested for thousands of cycles



- Space efficiency
 - Frees 100% of surface board area
 - Eliminates 2–10 mm² per resistor
- Thermal stability
 - Superior performance vs surface-mount resistors
- Signal integrity
 - Lower insertion loss
 - Improved phase consistency
- Cost efficiency
 - Reduces secondary placement and reflow steps
- Scalability
 - Suitable for prototyping and mass production
- Weight reduction
 - Ideal for aerospace applications



Resistance Equation

- Resistor value = sheet resistivity x ratio of element length to width
 - $R = R_s \times (L/W)$
 - R_s tolerance of $\pm 5-8\%$

Sources of Variation

- Lithography-controlled dimensions
- Geometry tolerance dominates
- Smaller resistors are expected to have higher resistor tolerance
- PCB processing can add +10-15%

• Typical Overall Tolerance

- $\pm 15-20\%$
- Laser trimming rarely required

For RF applications, performance variation is dominated by geometry and parasitics, not nominal resistance tolerance.



- Very high-power dissipation in a small area
- Late-stage value trimming required
- Applications requiring post-assembly tuning flexibility
- Low-frequency, cost-only designs

Note: Maximum Power Handling Calculators are available



- 1) Identify resistors in RF signal paths
- 2) Replace vias + chips with planar elements
- 3) Simulate with EM solver
- 4) Validate geometry tolerance
- 5) Include calibration impact



- Most information is generated by customers
- Not all information is shared
- Decided to build our own test vehicles
 - Two different copper profiles
 - Two different materials (Thermoset and Thermoplastic)
 - Two different designs based on frequency (Ka and V band)
 - Microstrip and Stripline
 - Compare with the best available surface-mount RF resistor



- Compatible with PTFE-based laminates
- Compatible with PPO-based and other advanced thermosets
- Compatible with Polyimide Flex materials
- Supports microstrip and stripline
- Available across 10–1000 Ω/sq



Summary: Why Embedded Resistors?

- Lower parasitics → better array accuracy
- Scalable to mmWave
- Higher density, stability, reliability
- 50+ years proven in mission-critical systems
- U.S. manufacturing



Information on both Ohmega and Ticer product lines

Note: Registration required to access Technical Library



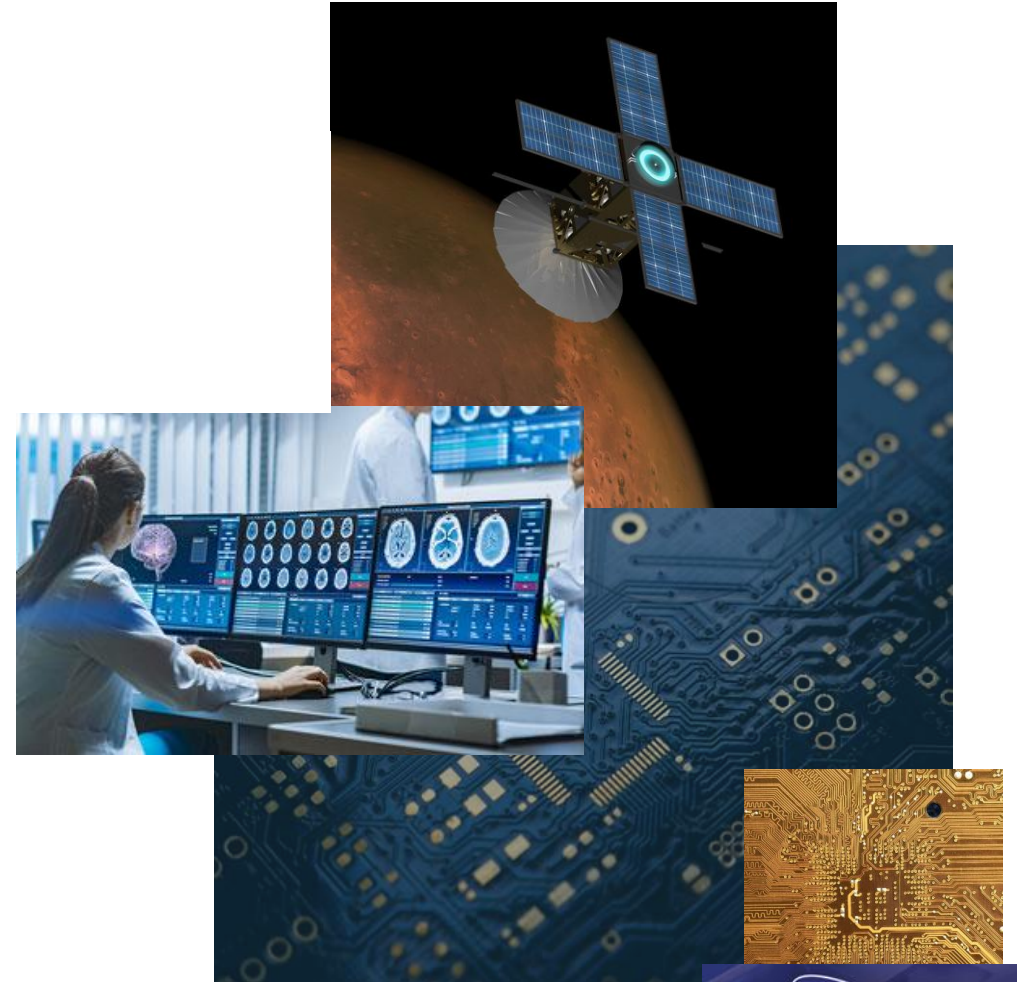
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Questions?



ΩmegaTicer

Thank You!

